



深圳市佑驰电子有限公司

Specification for Approval

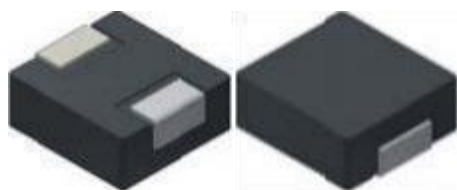
产品名称: 一体系列电感
规格型号: HCMA-1350-8R2-M
产品编号:
日 期: 2026-05-20

- 1、本承认书的内容更改需经过双方确认，任一方单独的修改均视为无效。
- 2、本承认书在送达客户后，请给予承认并即签回，如无签回下订单的，我司有权以此承认书标准生产，并表示购买方默认许可。

核准	审核	制作
	Aaron	Ada

High Current, Power Inductors

HCMA-1350-8R2-M Power Choke



Description

- Halogen Free
- 125 °C maximum total temperature operation
- Powder iron core material
- Magnetically shielded, low EMI
- High current carrying capacity, Low core losses
- Frequency range up to 5 MHz
- RoHS compliant

Applications

- Voltage Regulator Module (VRM)
- Multi-phase regulators
- Point-of-load modules
- Smart phone POL modules
- SSD modules
- Notebook regulators
- Battery power systems
- Graphics cards
- Data networking and storage systems

Environmental Data

- Storage temperature range: -55 °C to +125 °C
- Operating temperature range: -55 °C to +125 °C (ambient plus self-temperature rise)
- Solder reflow temperature: J-STD-020 D compliant

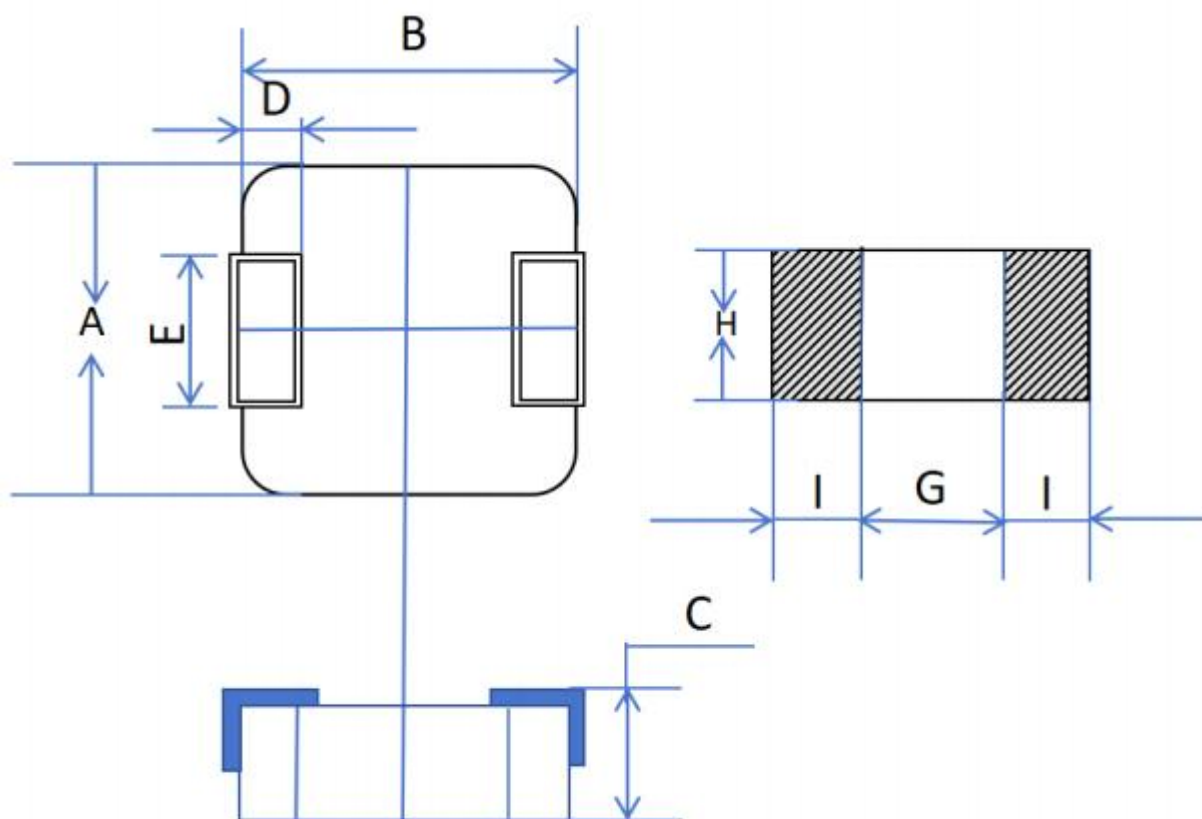
Description												
HCMA-1350-8R2-M				8.2μH				±20 %				
Model				Inductance Value				Inductance Tolerance				
Global Part Number												
H	C	M	A	1	3	5	0	8	R	2	M	
Product Series				Dimensions				Inductance Value				Tol.

Part Number	L0 Inductance (μ H)	Irms(A) TYP	Isat(A) TYP	DCR m Ω	
				TYP	MAX
HCMA-1350-8R2-M	8.2 μ H $\pm$ 20%	9.5	13.0	15.5	20.0

Notes

1. All test data is referenced to 25 °C ambient
 2. Operating temperature range - 55 °C to + 125 °C
 3. Idc(A):DC current (A) that will cause an approximate Δ T of 40 °C (reference ambient temperature is 25 °C)
 4. Isat(A):DC current (A) that will cause L0 to drop approximately 30 %
 5. The part temperature (ambient + temp rise) should not exceed 125 °C under worst case operating conditions.
- Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

•Dimensions-mm



A:	12.8±0.5	B:	13.8±0.5	C :	5.0MAX
D:	2.5±0.5	E:	3.8±0.5	G:	6.0Ref
H:	5.0Ref	I:	4.25Ref		

REFLOW PROFILE

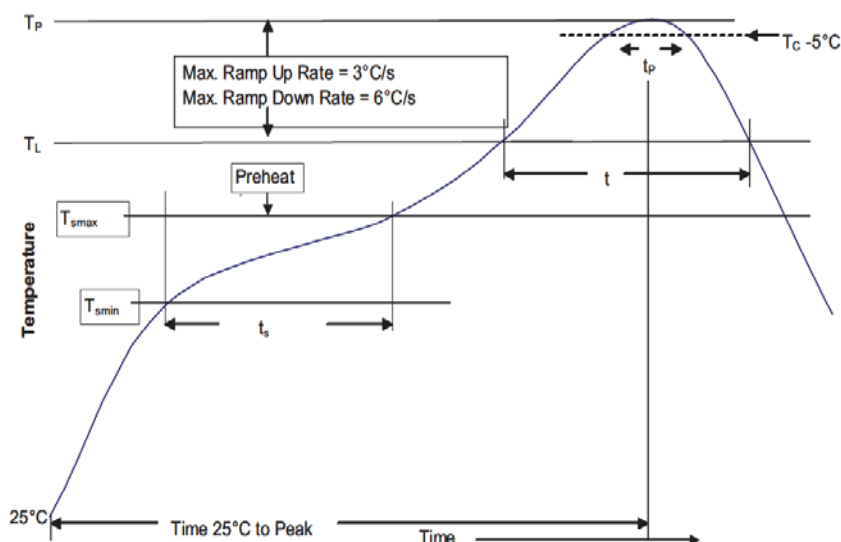


Table 1 - Standard SnPb Solder (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5mm	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T_{smin})	100°C	150°C
• Temperature max. (T_{smax})	150°C	200°C
• Time (T_{smin} to T_{smax}) (t_s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T_{smax} to T_p	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T_L)	183°C	217°C
Time at liquidous (t_L)	60-150 Seconds	60-150 Seconds
Peak package body temperature (T_p)*	Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_c)	20 Seconds**	30 Seconds**
Average ramp-down rate (T_p to T_{smax})	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

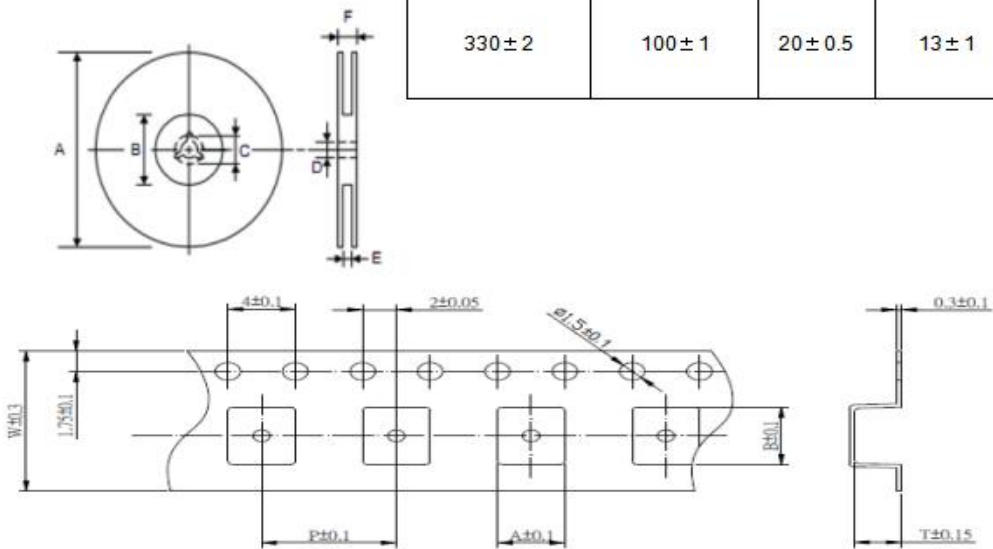
* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

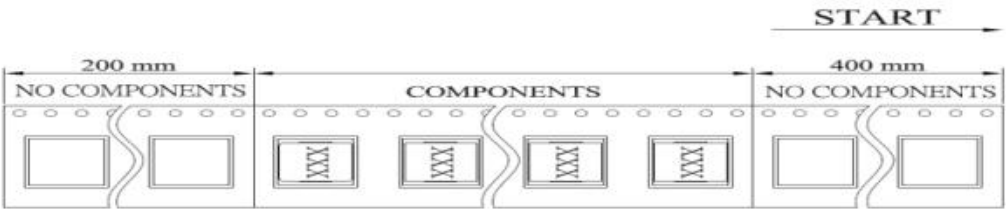
产品包装 Packaging

PACKAGE:

A	B	C	D	E	F
330±2	100±1	20±0.5	13±1	24.8±1	32.2±1



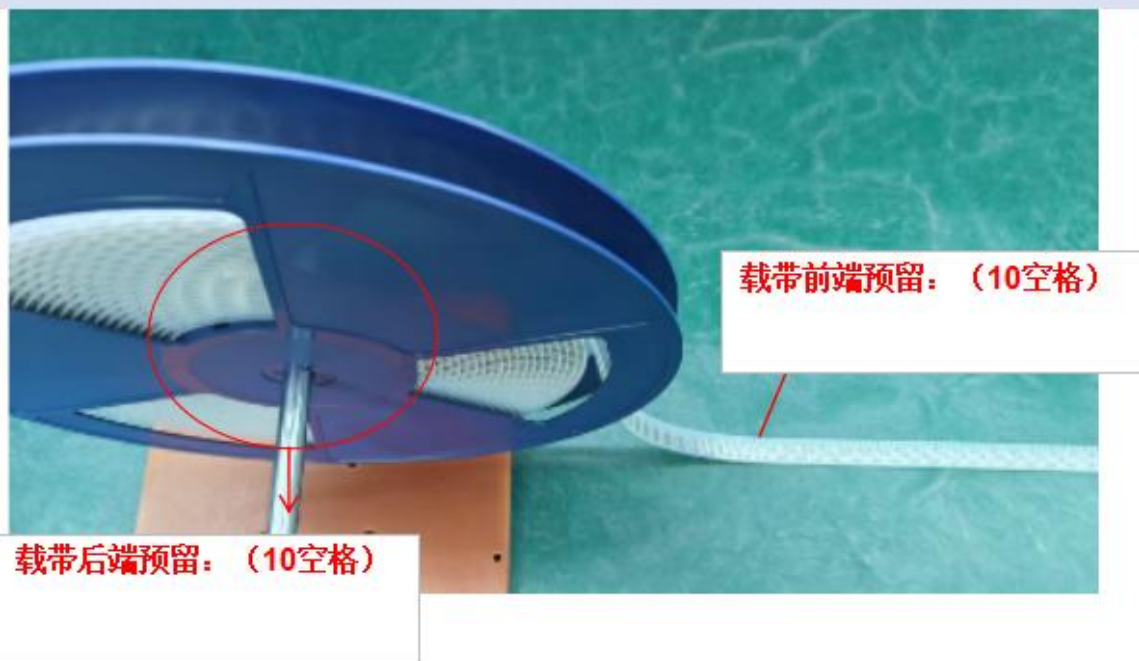
A	B	W	P	T
13.5	14.2	24	16	5.3



包装数量 Packing quantity

Series	卷盘REEL (PCS)
HCMA-1350	500

注：包装载带前/后预留空载带长度。载带前端预留：10个单元格，
载带后端预留：10个单元格。



Series	卷盘REEL (PCS)	内盒340*30*340 全盖	纸箱Carton (PCS) (358*358*187)
HCMA-1350	500	500(1盘)	2000(4内盒)

